

Listing of Claims:

Claims 1-24 (Canceled)

Claim 25: A method of making a probe substrate comprising:

providing a substrate as a premanufactured component, said substrate comprising a predetermined wiring pattern with contacts on a surface of said substrate,

thereafter receiving design data regarding a semiconductor device to be tested by said substrate, said design data including locations of test points on said semiconductor device,

adding one or more customization layers to said surface of said substrate,

adding a plurality of probes for contacting said test points on said semiconductor device to an outer one of said customization layers, said customization layers electrically connecting selected ones of said contacts on said surface of said substrate with selected ones of said plurality of probes.

Claim 26: The method of claim 1, wherein at least one of said test points protrudes from a surface of said semiconductor device, and said plurality of probes includes at least one corresponding probe configured to contact said protruding test point.

Claim 27: The method of claim 26, wherein said at least one corresponding probe is selected from a group consisting of a pad, a recess, and a socket.

Claim 28: The method of claim 25, wherein said customization layers include at least one embedded electrical circuit element.

Claim 29: The method of claim 25, wherein said customization layers include at least two layers, and said layers are added to said substrate one layer at a time.

Claim 30: The method of claim 25, wherein said customization layers include at least two layers, and said layers are formed apart from said first component and then joined to said first component.